



Product Change Notification

Change Notification #: 116434 - 00
Change Title: Intel® SSD 660p Series,
PCN 116434-00, Product Design, Label,
Transport Media, Firmware and Package
update
Date of Publication: August 23, 2018

Key Characteristics of the Change:

Product Design, Label, Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 7, 2018
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Description of Change to the Customer:

The Intel® SSD 660p Series SKUs listed in the products affected table below will have the firmware version updated from 001C to 002C. The changes in the new firmware version are incremental improvements from previous version. Inventory will transition in the Intel factory on or beyond the above date to replace older firmware version with the latest version. The product label will change with the new version of the firmware.

- Change to retail box packaging for MMs 984872 & 984875

Current



New



- Change to retail box packaging for MM 981634

Current



New



Customer Impact of Change and Recommended Action:

Since the firmware update has incremental improvement over the previous version, Intel anticipates no product impact with this firmware, and re-qualification is not recommended. The packaging change will not affect the Form, Fit or Function of the product.

Customer should be aware of these packaging changes and take any steps for incoming and processing to accommodate the new packages.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

* Other names and brands may be claimed as the property of others.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#	Pre Change TA	Pre Change SA	Post Change TA	Post Change SA
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW512G801	976802	J93118-100	J93121-100	J93118-101	J93121-101
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW010T801	976803	J93119-100	J93130-100	J93119-101	J93130-101
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW020T801	976804	J93120-100	J93132-100	J93120-101	J93132-101
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW512G8X1	978348	K10628-100	K10634-100	K10628-101	K10634-101
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW512G8XT	978349	K10629-100	K10634-100	K10629-101	K10634-101
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW010T8X1	978350	J10631-100	K10635-100	J10631-101	K10635-101
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW020T8X1	978351	K10633-100	K10636-100	K10633-101	K10636-101
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic 10 Pack	SSDPEKNW512G810	981634	K22966-100	J93121-100	K22966-101	J93121-101
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW020T8XT	984872	K31002-100	K31005-100	K31002-101	K31005-101
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW010T8XT	984875	K31001-100	K31003-100	K31001-101	K31003-101

PCN Revision History:

Date of Revision:
August 23, 2018

Revision Number:
00

Reason:
Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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